

主要材料/BOM 清单信息(Information of Material/BOM list):

材料			描述	供应商
1	基板	6C105_E01_H_FP	240X76. 3X0. 17	客供
2	晶圆	N51712	835*435 (μ m ²) *150 A芯 (U1)	客供
3	助焊剂	TACFLUX 026S	/	钢泰
4	塑封料	G311ACCver.GR	/	住友电木
5	分离膜	TB 50 μ m*142mm TOWA	/	TOWA

说明:

HY-PX-1199-015 A 是 HY-PX-1199-011 A 升级图纸，原图纸作废，具体变更信息如下:

1. 修正“底部示意图”图示；（附页2）
2. 调整产品名称；由“FX14102”变更为“FX14102_SAV11”。

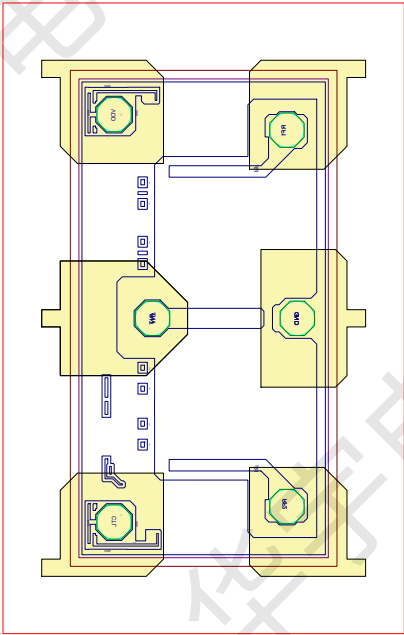
塑封模具	C模
切割道宽度	0. 2mm

拟制 Prepared by		制图日期 Create Date	2026/4/17	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

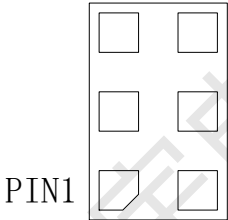
*温馨提示: 图纸为产品下线生产的唯一依据, 请您认真确认, 我司依据您回签后的图纸生产, 如图纸错误会产生不可估量损失, 谢谢!
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram				客户代码 Customer No.		1199		线图号 Drawing No.		HY-PX-1199-015 A				页码 Page 2 / 4	
				产品名称 Product Type		FX14102_SAV11				封装外型 PKG Type		LGA6L(1.1X0.7X0.52-P0.4)			
助焊剂 Flux		/		/		/		/		塑封料型号(绿色环保) Compound Type (Green)				基板编码 Substrate No.	
TACFLUX 026S		/		/		/		/		首选(Preferred): G311ACVer.GR 备选(Optional):				6C105_E01_H_FP	
客户图号 Customer drawing NO.															

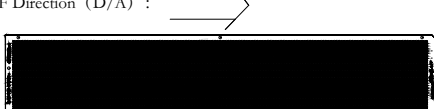
样品验证，禁止量产！



PIN1



底部示意图

框架传送方向（装片）： L/F Direction (D/A) :		实物图： Chip photo:		特殊说明 Special Instructions :	
					
					
按单颗显示方向进料					

序号	芯片名称	Die ID	芯片尺寸 (with scribe line)	划片道 宽度	圆片工艺	芯片厚度 UM	来料方式	Wafer material*	Bump type*	Bump composition*	Min bump pitch (space + bump size)* UM	Min bump height* UM	Min bump diameter* UM
A芯 U1	N51712	N51712D01	865*465(μm²)	30um	NA	150um (不包含bump高度)	wafer	SOI	NA	NA	NA	70	60
拟制 Prepared by		制图日期 Create Date			2026/4/17			生效日期 Effective Date			客户确认签字/盖章： Customer Signature		
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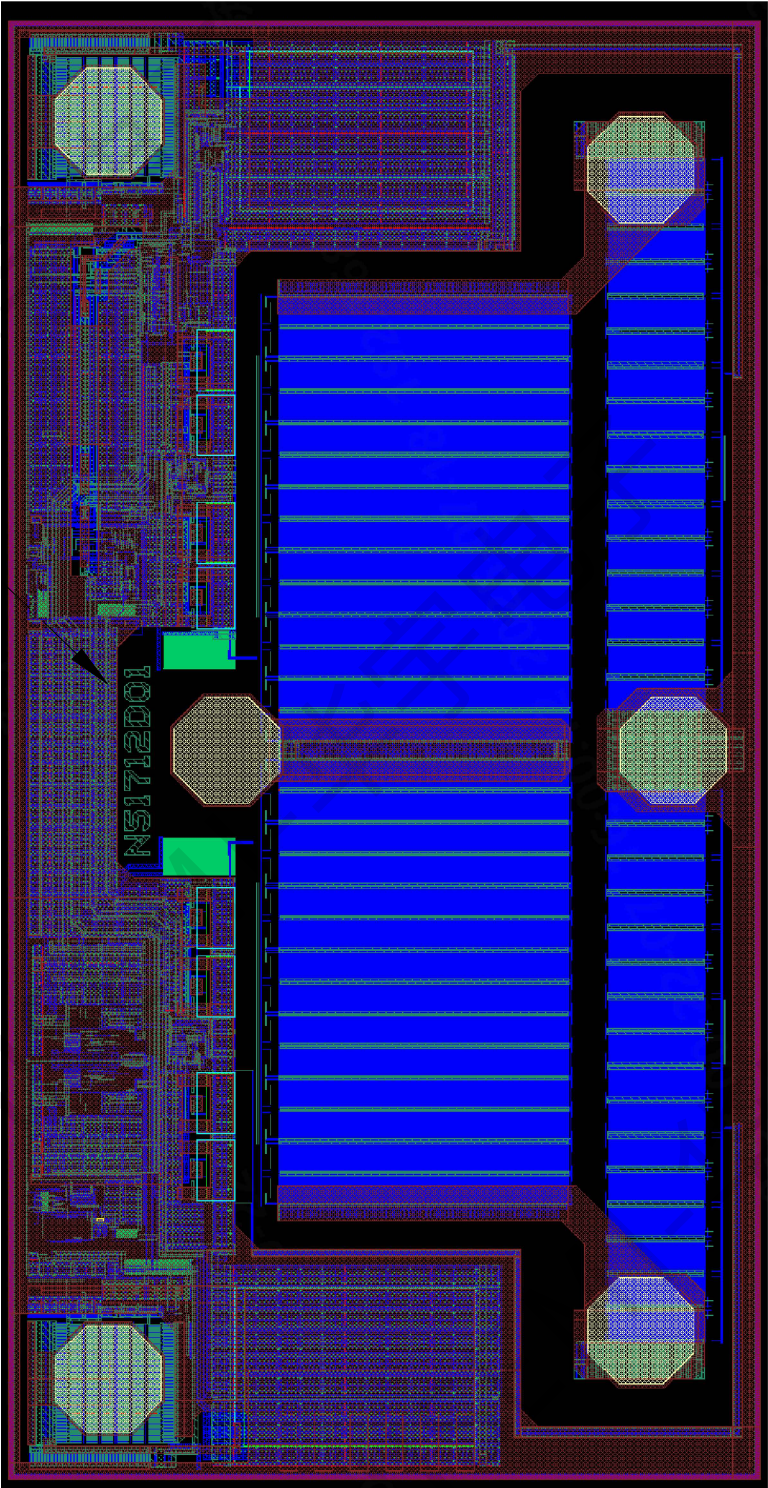
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	产品名称 Product Type	FX14102_SAV11		封装外型 PKG Type	LGA6L(1.1X0.7X0.52-P0.4)	

U1 ball map图 (TOP view)

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按目标区域取DIE：
ID: N51712D01

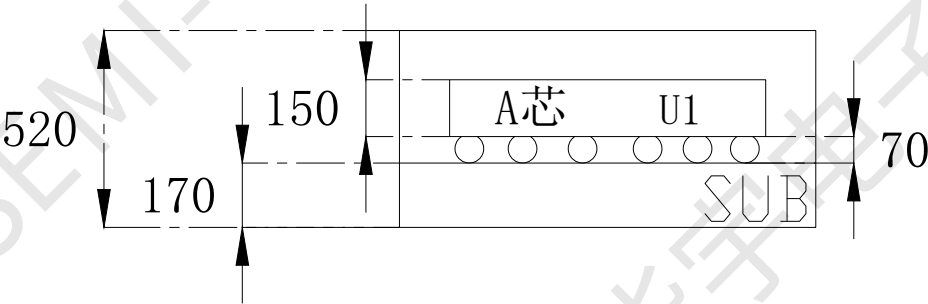


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